

Subject card

	Decimal Mathematical Magnetic Action 1900 00010070									
Subject name and code	Design Methodology and Manufacturing, PG_00048073									
Field of study	Electronics and Telecommunications									
Date of commencement of studies	October 2020		Academic year of realisation of subject			2022/2023				
Education level	first-cycle studies		Subject group			Optional subject group Subject group related to scientific research in the field of study				
Mode of study	Full-time studies		Mode of delivery			at the university				
Year of study	3		Language of instruction			Polish				
Semester of study	5		ECTS credits			1.0				
Learning profile	general academic profile		Assessment form			assessment				
Conducting unit	Department of Metrol	Department of Metrology and Optoelectronics -> Faculty of Electronics, Telecommunications and Ir					d Informatics			
Name and surname	Subject supervisor	- 1		•						
of lecturer (lecturers)	Teachers			dr inż. Arkadiusz Szewczyk						
(dr inż. Arkadiusz Szewczyk dr inż. Jacek Cichosz							
Lesson types and methods	Lesson type	Lecture	Tutorial	Laboratory	Projec	t	Seminar	SUM		
of instruction	Number of study hours	15.0	0.0	0.0	0.0		0.0	15		
	E-learning hours inclu	uded: 0.0								
Learning activity and number of study hours	Learning activity	Participation in didactic classes included in study plan		Participation in consultation hours		Self-study		SUM		
	Number of study hours	15		1.0	1.0			25		
Subject objectives	Give the knowledge of technology of design and manufacturing of electronic equipment.									
Learning outcomes	Course outcome		Subject outcome			Method of verification				
Learning outcomes	Course out	come	Subj	cci outcome			viction of veril	loation		
Learning outcomes	[K6_W32] Knows the functions and methodesign and optimizat analogue and digital electronic systems	e parameters, ds of analysis, ion of	knows how to	choose and ap iniques for des			Assessment of			
Learning outcomes	[K6_W32] Knows the functions and methodesign and optimizat analogue and digital	e parameters, ds of analysis, ion of circuits and a, according to as, and make lity, system or specific to the suitable b, tools and engineering as, applying to the field of e gained in	knows how to tools and tech electronic dev is able to desi with the given	choose and ap iniques for des	igning nce and	[SW1] / knowle	Assessment of dge	factual		
Subject contents	[K6_W32] Knows the functions and methodesign and optimizat analogue and digital electronic systems [K6_U03] can design required specification a simple device, facilicarry out a process, field of study, using smethods, techniques materials, following estandards and norms technologies specific study and experience the professional engi	e parameters, ds of analysis, ion of circuits and a circuits a circuits a circuit a circuits a	is able to desi with the given build a simple engineering of anufacturing3. closure and moth contacts; materials. 11 outning technologiesigning of padques of printed paration of fabri. Cooling systematicals with the given build a simple engineering of anufacturing3. closure and moth contacts; materials. 11 outning technologiesigning of padques of printed paration of fabri. Cooling systematicals.	electronic devirence of the section	ces and iice ces and iice 5. Interniles. 7. (n technielectroriponen dering, units for the manufacentation	[SW1] A knowled [SW1] A fulfilme system lesigning al conn Cabling. iques: so iic devicts for the refront computer to turing to cturing to 18. Gr	s.2. Designing g and construct ections between Parameters or oldering, wire-ties mounting the rough-hole and coldering. 13. For each nology on p 16. Electronic ounding and si	of electronic tition en modules: f cables, wrapping, echnology on d surface Production ling, for rinted board Design hielding		
	[K6_W32] Knows the functions and method design and optimizat analogue and digital electronic systems [K6_U03] can design required specification a simple device, facilicarry out a process, field of study, using smethods, techniques materials, following standards and normstechnologies specific study and experience the professional engienvironment 1. Basic problems of devices allowing required and separable. If materials for conduction crimping. 9. Manual a environment; lead-free mounting technology units for automatic medepositing of glue and design. 15. Construct Automation (EDA) so techniques. Designing	e parameters, ds of analysis, ion of circuits and a circuits a circuits a circuit a circuits a	is able to desi with the given build a simple engineering of anufacturing3. closure and moth contacts; materials. 11 outning technologiesigning of padques of printed paration of fabri. Cooling systematicals with the given build a simple engineering of anufacturing3. closure and moth contacts; materials. 11 outning technologiesigning of padques of printed paration of fabri. Cooling systematicals.	electronic devirence of the section	ces and iice ces and iice 5. Interniles. 7. (n technielectroriponen dering, units for the manufacentation	[SW1] A knowled [SW1] A fulfilme system lesigning al conn Cabling. iques: so iic devicts for the refront computer to turing to cturing to 18. Gr	s.2. Designing g and construct ections between Parameters or oldering, wire-ties mounting the rough-hole and coldering. 13. For each nology on p 16. Electronic ounding and si	of electronic tition en modules: f cables, wrapping, echnology on d surface Production ling, for rinted board Design hielding		

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Assessment methods	Subject passing criteria	Passing threshold	Percentage of the final grade		
and criteria	Writting exam	50.0%	100.0%		
Recommended reading	Basic literature	Ryszard Kisiel:"Podstawy technologii montażu dla elektroników", BTC 2012			
	Supplementary literature	Krystyna Bukart, Halina Hackiewicz: "Lutowanie bezołowiowe", BTC 2007			
	eResources addresses	Adresy na platformie eNauczanie:			
Example issues/ example questions/ tasks being completed	CAD software, soldering, PCB asser	mbly, devices outlines, connections,	grounding, shielding.		
Work placement	Not applicable				

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